

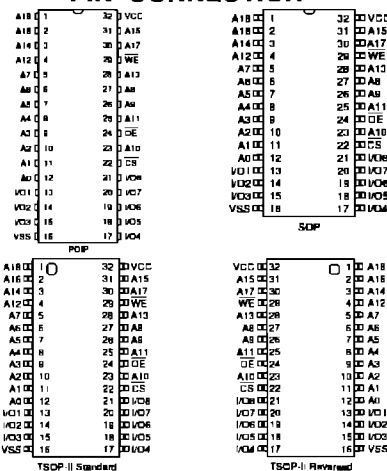
### DESCRIPTION

The HY628400-I is a high-speed, low power and 524,288 x 8-bits CMOS static RAM fabricated using Hyundai's high performance twin tub CMOS process technology. This high reliability process coupled with innovative circuit design techniques, yields maximum access time of 55ns. The HY628400-I has a data retention mode that guarantees data to remain valid at a minimum power supply voltage of 2.0 volt. Using CMOS technology, supply voltages from 2.0 to 5.5 volt have little effect on supply current in data retention mode. Reducing the supply voltage to minimize current drain is unnecessary with the HY628400-I Series. -40°C to 85°C operating temperature range is suitable for industrial use.

### FEATURES

- Extended temperature range : -40°C to 85°C
- High speed-55/70/85/100ns (max.)
- Low power consumption
  - Operating : 25 mW (typ.)
  - Standby (CMOS) : 10 µW (typ.)
- Single 5V± 10% power supply
- Battery backup
  - 2.0V (min.) data retention
- Fully static operation
  - No clock or refresh required
- TTL compatible inputs and outputs
- Tri-state output
- Standard pin configuration
  - 32 pin 500 mil PDIP
  - 32 pin 525 mil SOP
  - 32 pin 400 mm TSOP - II

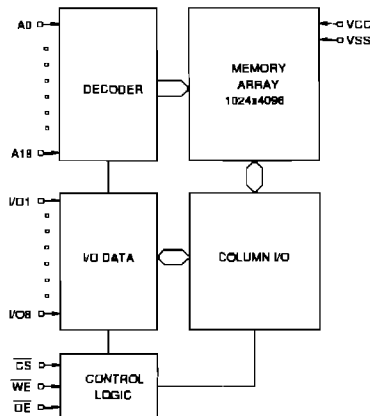
### PIN CONNECTION



### PIN DESCRIPTION

| Pin Name  | Pin Function      |
|-----------|-------------------|
| CS        | Chip Select       |
| WE        | Write Enable      |
| OE        | Output Enable     |
| A0-A18    | Address Inputs    |
| I/O1-I/O8 | Data Input/Output |
| Vcc       | Power (+ 5V)      |
| Vss       | Ground            |

### BLOCK DIAGRAM



**ABSOLUTE MAXIMUM RATINGS<sup>(1)</sup>**

| SYMBOL         | PARAMETER                          | RATING       | UNIT     |
|----------------|------------------------------------|--------------|----------|
| VCC, VIN, VOUT | Power Supply, Input/Output Voltage | - 0.5 to 7.0 | V        |
| TA             | Operating Temperature              | - 40 to 85   | °C       |
| TBIAS          | Temperature under Bias             | - 10 to 125  | °C       |
| TSTG           | Storage Temperature                | - 65 to 150  | °C       |
| Pd             | Power Dissipation                  | 1.0          | W        |
| IOUT           | Data Output Current                | 50           | mA       |
| TSOLDER        | Lead Soldering Temperature & Time  | 250± 10      | °C • sec |

Note :

1. Stresses greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational of this specification is not implied. Exposure to absolute maximum rating conditions for extended period may affect reliability.

**RECOMMENDED DC OPERATING CONDITIONS**

(TA= -40°C to 85°C)

| SYMBOL | PARAMETER            | MIN.                | TYP. | MAX.      | UNIT |
|--------|----------------------|---------------------|------|-----------|------|
| VCC    | Power Supply Voltage | 4.5                 | 5.0  | 5.5       | V    |
| VIH    | Input High Voltage   | 2.2                 | -    | VCC + 0.5 | V    |
| VIL    | Input Low Voltage    | -0.5 <sup>(1)</sup> | -    | 0.8       | V    |

Note :

1. VIL = -3.0V for pulse width less than 50ns.

**TRUTH TABLE**

| MODE            | I/O OPERATION | CS | WE | OE |
|-----------------|---------------|----|----|----|
| Standby         | High-Z        | H  | X  | X  |
| Output Disabled | High-Z        | L  | H  | H  |
| Read            | Data Out      | L  | H  | L  |
| Write           | Data In       | L  | L  | X  |

Note :

1. H= VIH, L= VIL, X= Don't Care

**DC CHARACTERISTICS**

(TA= -40°C to 85°C, VCC= 5V ± 10%, unless otherwise specified.)

| SYMBOL           | PARAMETER                          | TEST CONDITIONS   | POWER | MIN. | TYP. | MAX. | UNIT |
|------------------|------------------------------------|---|-------|------|------|------|------|
| I <sub>LI</sub>  | Input Leakage Current              | V <sub>SS</sub> ≤ V <sub>IN</sub> ≤ V <sub>CC</sub>   |       | -1   | -    | 1    | μA   |
| I <sub>LO</sub>  | Output Leakage Current             | V <sub>SS</sub> ≤ V <sub>OUTS</sub> ≤ V <sub>CC</sub><br>CS = V <sub>IH</sub> or DE= V <sub>IH</sub> or WE= V <sub>IL</sub> |       | -1   | -    | 1    | μA   |
| I <sub>CC</sub>  | Operating Power Supply Current     | CS= V <sub>IL</sub><br>V <sub>IN</sub> = V <sub>IH</sub> or V <sub>IL</sub> , I <sub>I/O</sub> = 0mA                        |       | -    | 5    | 10   | mA   |
| I <sub>CC1</sub> | Average Operating Current          | CS = V <sub>IL</sub><br>Min. Duty Cycle= 100%, I <sub>I/O</sub> = 0mA   |       | -    | 50   | 70   | mA   |
| I <sub>SB</sub>  | TTL Standby Current (TTL Inputs)   | CS= V <sub>IH</sub>   |       | -    | 0.4  | 2    | mA   |
| I <sub>SB1</sub> | CMOS Standby Current (CMOS Inputs) | CS ≥ V <sub>CC</sub> - 0.2V   | L     | -    | 2    | 100  | μA   |
|                  |                                    |   | LL    | -    | 1    | 50   | μA   |
| V <sub>OL</sub>  | Output Low Voltage                 | I <sub>OL</sub> = 2.1mA   |       | -    | -    | 0.4  | V    |
| V <sub>OH</sub>  | Output High Voltage                | I <sub>OH</sub> = - 1.0mA   |       | 2.4  | -    | -    | V    |

Note :

1. Typical values are at VCC= 5.0V, TA= 25°C.

**AC CHARACTERISTICS**

(TA= -40°C to 85°C, VCC= 5V ± 10%, unless otherwise noted.)

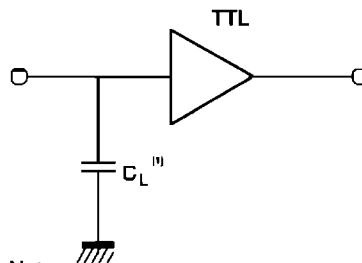
| #                  | SYMBOL | PARAMETER                       | -55  |      | -70  |      | -85  |      | -10  |      | UNIT |
|--------------------|--------|---------------------------------|------|------|------|------|------|------|------|------|------|
|                    |        |                                 | MIN. | MAX. | MIN. | MAX. | MIN. | MAX. | MIN. | MAX. |      |
| <b>READ CYCLE</b>  |        |                                 |      |      |      |      |      |      |      |      |      |
| 1                  | tRC    | Read Cycle Time                 | 55   | -    | 70   | -    | 85   | -    | 100  | -    | ns   |
| 2                  | tAA    | Address Access Time             | -    | 55   | -    | 70   | -    | 85   | -    | 100  | ns   |
| 3                  | tACS   | Chip Select Access Time         | -    | 55   | -    | 70   | -    | 85   | -    | 100  | ns   |
| 4                  | tOE    | Output Enable to Output Valid   | -    | 25   | -    | 35   | -    | 45   | -    | 50   | ns   |
| 5                  | tCLZ   | Chip Select to Low-Z Output     | 10   | -    | 10   | -    | 10   | -    | 10   | -    | ns   |
| 6                  | tOLZ   | Output Enable to Low-Z Output   | 5    | -    | 5    | -    | 5    | -    | 5    | -    | ns   |
| 7                  | tCHZ   | Chip Disable to High-Z Output   | 0    | 20   | 0    | 25   | 0    | 30   | 0    | 30   | ns   |
| 8                  | tOHZ   | Output Disable to High-Z Output | 0    | 20   | 0    | 25   | 0    | 30   | 0    | 30   | ns   |
| 9                  | tDH    | Output Hold from Address Change | 10   | -    | 10   | -    | 10   | -    | 10   | -    | ns   |
| <b>WRITE CYCLE</b> |        |                                 |      |      |      |      |      |      |      |      |      |
| 10                 | tWC    | Write Cycle Time                | 55   | -    | 70   | -    | 85   | -    | 100  | -    | ns   |
| 11                 | tCW    | Chip Select to End of Write     | 45   | -    | 60   | -    | 70   | -    | 80   | -    | ns   |
| 12                 | tAW    | Address Valid to End of Write   | 45   | -    | 60   | -    | 70   | -    | 80   | -    | ns   |
| 13                 | tAS    | Address Set-up Time             | 0    | -    | 0    | -    | 0    | -    | 0    | -    | ns   |
| 14                 | tWP    | Write Pulse Width               | 40   | -    | 50   | -    | 55   | -    | 60   | -    | ns   |
| 15                 | tWR    | Write Recovery Time             | 0    | -    | 0    | -    | 0    | -    | 0    | -    | ns   |
| 16                 | tWHZ   | Write to High-Z Output          | 0    | 20   | 0    | 25   | 0    | 30   | 0    | 30   | ns   |
| 17                 | tDW    | Data to Write Time Overlap      | 25   | -    | 30   | -    | 35   | -    | 40   | -    | ns   |
| 18                 | tDH    | Data Hold from Write Time       | 0    | -    | 0    | -    | 0    | -    | 0    | -    | ns   |
| 19                 | tOW    | Output Active from End of Write | 5    | -    | 5    | -    | 5    | -    | 5    | -    | ns   |

**AC TEST CONDITIONS**

( $T_A = -40^{\circ}\text{C}$  to  $85^{\circ}\text{C}$ ,  $V_{CC} = 5\text{V} \pm 10\%$ , unless otherwise specified.)

| PARAMETER                                | VALUE                                   |
|--|---|
| Input Pulse Level                        | 0.8V to 2.4V                            |
| Input Rise and Fall Time                 | 5ns                                     |
| Input and Output Timing Reference Levels | 1.5V                                    |
| Output Load                              | $C_L = 100\text{pF} + 1\text{TTL Load}$ |

**AC TEST LOADS**



Note :  
1. Including jig and scope capacitance.

**CAPACITANCE**

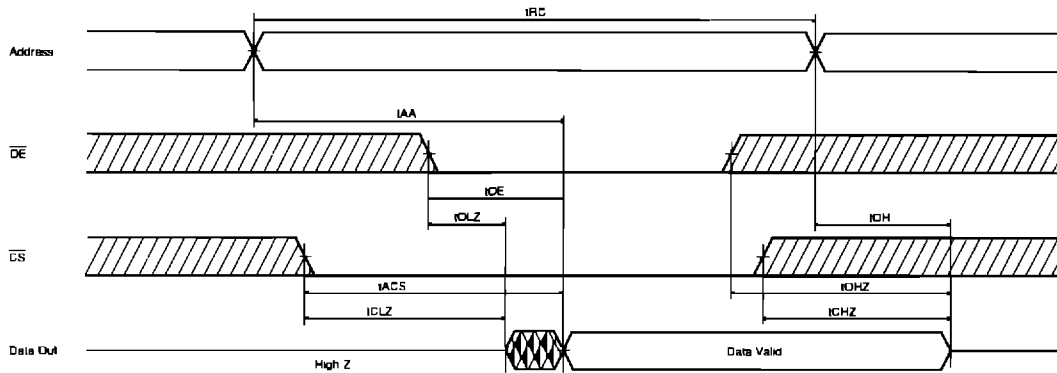
( $T_A = 25^{\circ}\text{C}$ ,  $f = 1\text{MHz}$ )

| SYMBOL    | PARAMETER                | CONDITION             | MAX. | UNIT |
|-----------|--------------------------|-----------------------|------|------|
| $C_{IN}$  | Input Capacitance        | $V_{IN} = 0\text{V}$  | 6    | pF   |
| $C_{I/O}$ | Input/Output Capacitance | $V_{I/O} = 0\text{V}$ | 8    | pF   |

Note :  
1. This parameter is sampled and not 100% tested.

**TIMING DIAGRAM**

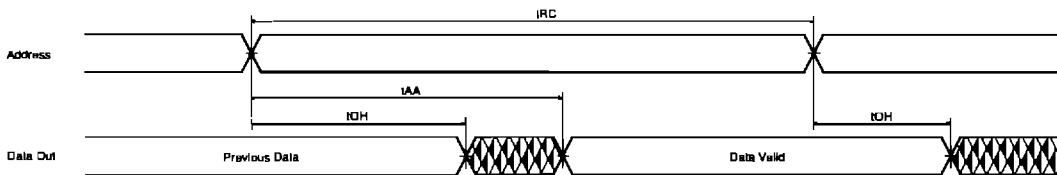
**READ CYCLE 1**



**Note (READ CYCLE):**

1. tCHZ and tOHZ are defined as the time at which the outputs achieve the open circuit conditions and are not referenced to output voltage levels.
2. At any given temperature and voltage condition, tCHZ max. is less than tCLZ min. both for a given device and from device to device.
3. WE is high for read cycle.

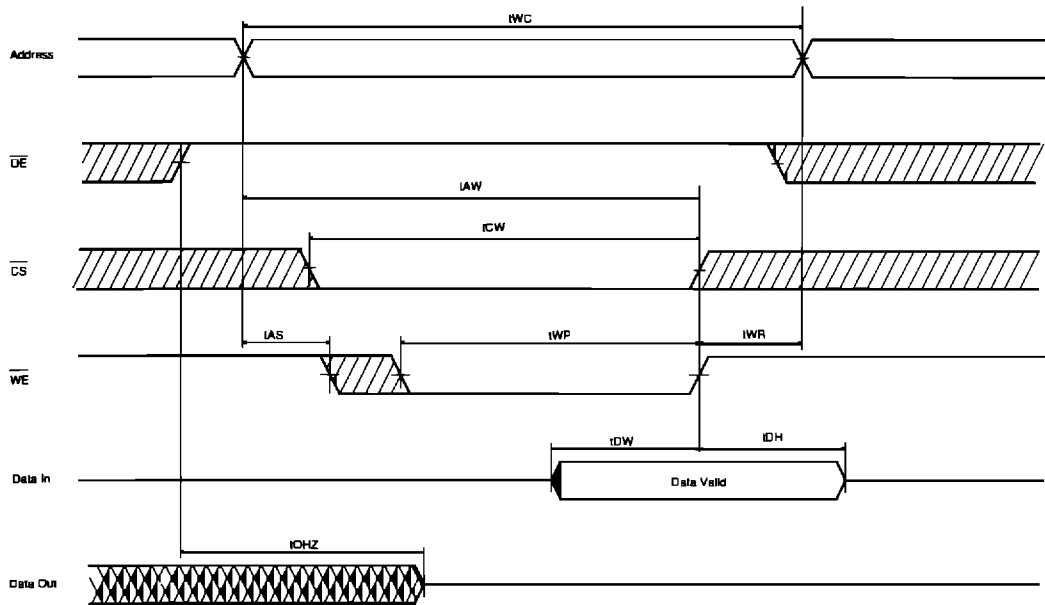
**READ CYCLE 2**



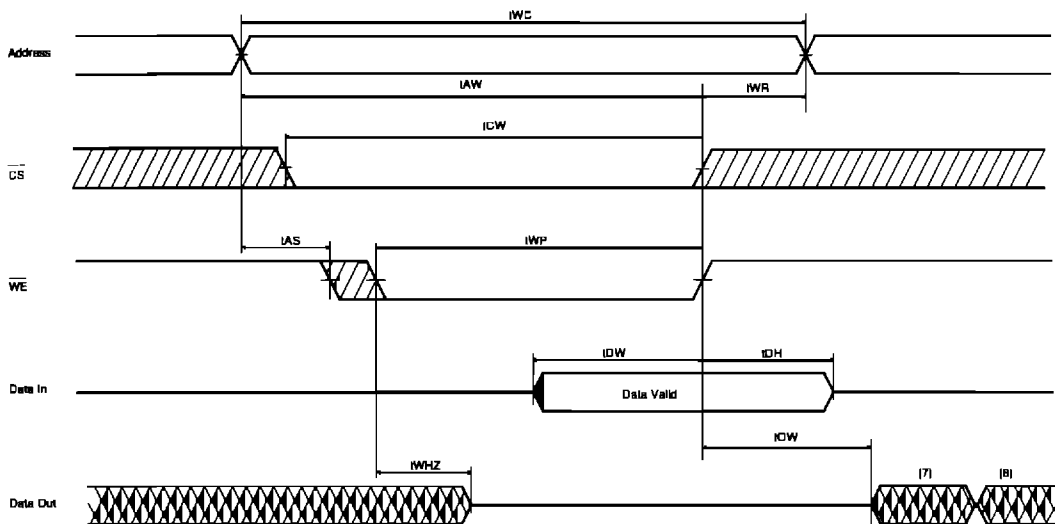
**Note(READ CYCLE):**

1. WE is high for read cycle.
2. Device is continuously selected CS= VIL.
3. OE= VIL.

**WRITE CYCLE 1 (OE Clocked)**



**WRITE CYCLE 2 (OE Low Fixed)**



**Note (WRITE CYCLE):**

1. A write occurs during the overlap of a low  $\overline{CS}$  and a low  $\overline{WE}$ . A write begins at the latest transition among  $\overline{CS}$  going low, and  $\overline{WE}$  going low. A write ends at the earliest transition among  $\overline{CS}$  going high and  $\overline{WE}$  going high.  $t_{wp}$  is measured from the beginning of write to the end of write.
2.  $t_{ow}$  is measured from the later of  $\overline{CS}$  going low to end of write.
3.  $t_{as}$  is measured from the address valid to the beginning of write.
4.  $t_{wr}$  is measured from the end of write to the address change.  $t_{wr}$  applied in case a write ends as  $\overline{CS}$  or  $\overline{WE}$  going high.
5. If  $\overline{OE}$  and  $\overline{WE}$  are in the read mode during this period, the I/O pins are in the output low-Z state, inputs of opposite phase of the output must not be applied because bus contention can occur.
6. If  $\overline{CS}$  goes low simultaneously with  $\overline{WE}$  going low or after  $\overline{WE}$  going low, the outputs remain in high impedance state.
7.  $D_{out}$  is the same phase of latest written data in this write cycle.
8.  $D_{out}$  is the read data of the new address.



**DATA RETENTION CHARACTERISTICS**

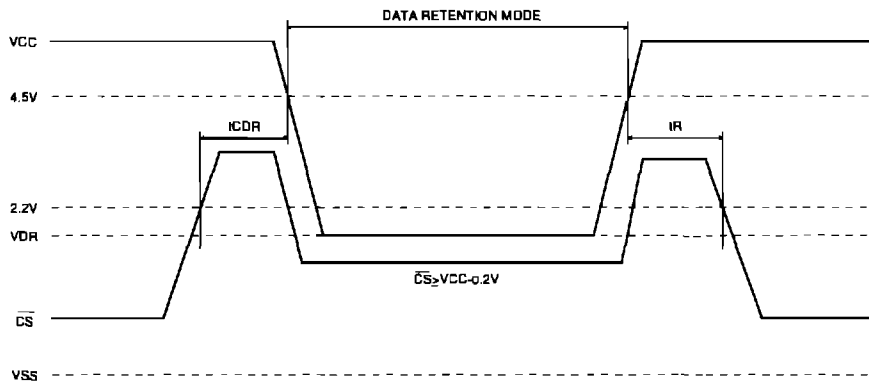
(TA= -40°C to 85°C)

| SYMBOL | PARAMETER                           | TEST CONDITION                                | POWER | MIN.               | TYP. | MAX. | UNIT |
|--------|-------------------------------------|---|-------|--------------------|------|------|------|
| VDR    | Vcc for Data Retention              | CS ≥ VCC-0.2V<br>VSS ≤ VIN ≤ VCC              |       | 2.0                | -    | -    | V    |
| ICCDR  | Data Retention Current              | VCC= 3.0V<br>CS ≥ VCC-0.2V<br>VSS ≤ VIN ≤ VCC | L     | -                  | 1    | 50   | μA   |
|        |                                     |   | LL    | -                  | 0.5  | 30   | μA   |
| tCDR   | Chip Disable to Data Retention Time | See Data Retention Timing Diagram             |       | 0                  | -    | -    | ns   |
| IR     | Operating Recovery Time             |   |       | tRC <sup>[2]</sup> | -    | -    | ns   |

Notes :

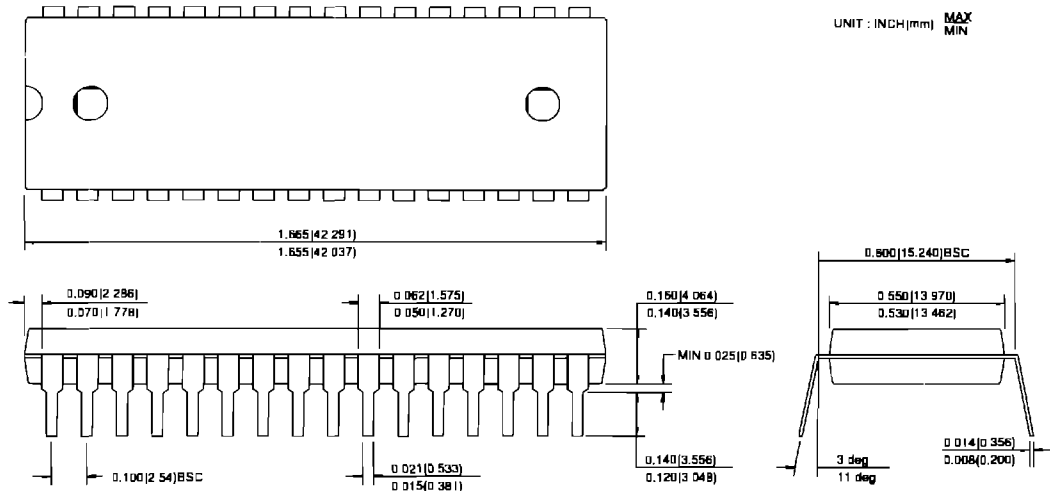
1. Typical values are at the condition of TA= 25°C.
2. tRC is read cycle time.

**DATA RETENTION TIMING DIAGRAM 1**

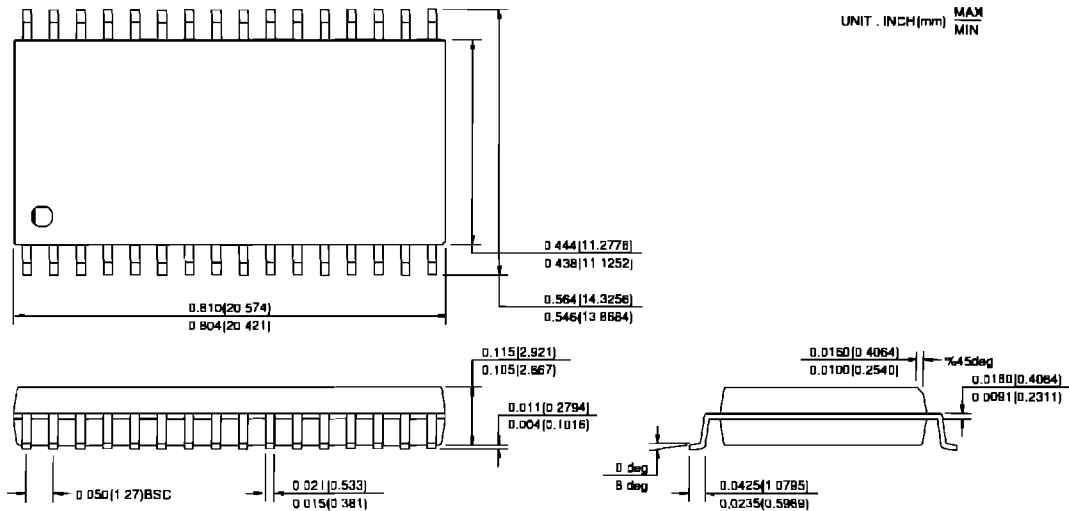


**PACKAGE INFORMATION**

**600 mil 32 pin Plastic Dual In-line Package (P)**



**525 mil 32 pin Small Outline Package (G)**



**ORDERING INFORMATION**

| <b>PART NO.</b> | <b>SPEED</b> | <b>POWER</b> | <b>PACKAGE</b>   |
|-----------------|--------------|--------------|------------------|
| HY62B400LP-I    | 55/70/85/100 | L-part       | PDIP             |
| HY62B400LLP-I   | 55/70/85/100 | LL-part      | PDIP             |
| HY62B400LG-I    | 55/70/85/100 | L-part       | SOP              |
| HY62B400LLG-I   | 55/70/85/100 | LL-part      | SOP              |
| HY62B400LT2-I   | 55/70/85/100 | L-part       | TSOP-II Standard |
| HY62B400LLT2-I  | 55/70/85/100 | LL-part      | TSOP-II Standard |
| HY62B400LR2-I   | 55/70/85/100 | L-part       | TSOP-II Reversed |
| HY62B400LLR2-I  | 55/70/85/100 | LL-part      | TSOP-II Reversed |